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### Understanding Embedded - FPGAs (Field Programmable Gate Array)


Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	1840
Number of Logic Elements/Cells	29440
Total RAM Bits	1105920
Number of I/O	290
Number of Gates	-
Voltage - Supply	1.16V ~ 1.24V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep4cgx30cf23i7n">https://www.e-xfl.com/product-detail/intel/ep4cgx30cf23i7n</a>

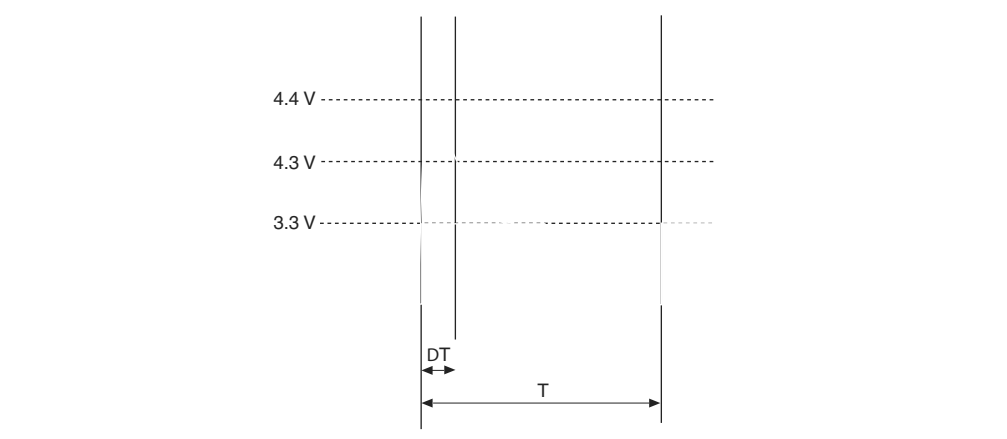
 A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

**Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices**

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
$V_i$	AC Input Voltage	$V_i = 4.20$	100	%
		$V_i = 4.25$	98	%
		$V_i = 4.30$	65	%
		$V_i = 4.35$	43	%
		$V_i = 4.40$	29	%
		$V_i = 4.45$	20	%
		$V_i = 4.50$	13	%
		$V_i = 4.55$	9	%
		$V_i = 4.60$	6	%

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as  $([\Delta T]/T) \times 100$ . This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.

**Figure 1–1. Cyclone IV Devices Overshoot Duration**



**Table 1-4. Recommended Operating Conditions for Cyclone IV GX Devices (Part 2 of 2)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CCA_GXB</sub>	Transceiver PMA and auxiliary power supply	—	2.375	2.5	2.625	V
V <sub>CCL_GXB</sub>	Transceiver PMA and auxiliary power supply	—	1.16	1.2	1.24	V
V <sub>I</sub>	DC input voltage	—	-0.5	—	3.6	V
V <sub>O</sub>	DC output voltage	—	0	—	V <sub>CCIO</sub>	V
T <sub>J</sub>	Operating junction temperature	For commercial use	0	—	85	°C
		For industrial use	-40	—	100	°C
t <sub>RAMP</sub>	Power supply ramp time	Standard power-on reset (POR) <sup>(7)</sup>	50 μs	—	50 ms	—
		Fast POR <sup>(8)</sup>	50 μs	—	3 ms	—
I <sub>Diode</sub>	Magnitude of DC current across PCI-clamp diode when enabled	—	—	—	10	mA

**Notes to Table 1-4:**

- (1) All V<sub>CCA</sub> pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.
- (2) You must connect V<sub>CCD\_PLL</sub> to V<sub>CCINT</sub> through a decoupling capacitor and ferrite bead.
- (3) Power supplies must rise monotonically.
- (4) V<sub>CCIO</sub> for all I/O banks must be powered up during device operation. Configurations pins are powered up by V<sub>CCIO</sub> of I/O Banks 3, 8, and 9 where I/O Banks 3 and 9 only support V<sub>CCIO</sub> of 1.5, 1.8, 2.5, 3.0, and 3.3 V. For fast passive parallel (FPP) configuration mode, the V<sub>CCIO</sub> level of I/O Bank 8 must be powered up to 1.5, 1.8, 2.5, 3.0, and 3.3 V.
- (5) You must set V<sub>CC\_CLKIN</sub> to 2.5 V if you use CLKIN as a high-speed serial interface (HSSI) refclk or as a DIFFCLK input.
- (6) The CLKIN pins in I/O Banks 3B and 8B can support single-ended I/O standard when the pins are used to clock left PLLs in non-transceiver applications.
- (7) The POR time for Standard POR ranges between 50 and 200 ms. V<sub>CCINT</sub>, V<sub>CCA</sub>, and V<sub>CCIO</sub> of I/O Banks 3, 8, and 9 must reach the recommended operating range within 50 ms.
- (8) The POR time for Fast POR ranges between 3 and 9 ms. V<sub>CCINT</sub>, V<sub>CCA</sub>, and V<sub>CCIO</sub> of I/O Banks 3, 8, and 9 must reach the recommended operating range within 3 ms.

## ESD Performance

This section lists the electrostatic discharge (ESD) voltages using the human body model (HBM) and charged device model (CDM) for Cyclone IV devices general purpose I/Os (GPIOs) and high-speed serial interface (HSSI) I/Os. Table 1-5 lists the ESD for Cyclone IV devices GPIOs and HSSI I/Os.

**Table 1-5. ESD for Cyclone IV Devices GPIOs and HSSI I/Os**

Symbol	Parameter	Passing Voltage	Unit
V <sub>ESDHBM</sub>	ESD voltage using the HBM (GPIOs) <sup>(1)</sup>	± 2000	V
	ESD using the HBM (HSSI I/Os) <sup>(2)</sup>	± 1000	V
V <sub>ESDCDM</sub>	ESD using the CDM (GPIOs)	± 500	V
	ESD using the CDM (HSSI I/Os) <sup>(2)</sup>	± 250	V

**Notes to Table 1-5:**

- (1) The passing voltage for EP4CGX15 and EP4CGX30 row I/Os is ±1000V.
- (2) This value is applicable only to Cyclone IV GX devices.

## DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

### Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1-6 lists the I/O pin leakage current for Cyclone IV devices.

**Table 1-6. I/O Pin Leakage Current for Cyclone IV Devices <sup>(1), (2)</sup>**

Symbol	Parameter	Conditions	Device	Min	Typ	Max	Unit
$I_I$	Input pin leakage current	$V_I = 0\text{ V to }V_{CCIOMAX}$	—	-10	—	10	$\mu\text{A}$
$I_{OZ}$	Tristated I/O pin leakage current	$V_O = 0\text{ V to }V_{CCIOMAX}$	—	-10	—	10	$\mu\text{A}$

**Notes to Table 1-6:**

- (1) This value is specified for normal device operation. The value varies during device power-up. This applies for all  $V_{CCIO}$  settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).
- (2) The 10  $\mu\text{A}$  I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

### Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-7 lists bus hold specifications for Cyclone IV devices.

**Table 1-7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) <sup>(1)</sup>**

Parameter	Condition	V <sub>CCIO</sub> (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus hold high, sustaining current	V <sub>IN</sub> < V <sub>IL</sub> (minimum)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus hold low, overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus hold high, overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA

## Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1-12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

**Table 1-12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices <sup>(1)</sup>**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>PU</sub>	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	V <sub>CCIO</sub> = 3.3 V ± 5% <sup>(2), (3)</sup>	7	25	41	kΩ
		V <sub>CCIO</sub> = 3.0 V ± 5% <sup>(2), (3)</sup>	7	28	47	kΩ
		V <sub>CCIO</sub> = 2.5 V ± 5% <sup>(2), (3)</sup>	8	35	61	kΩ
		V <sub>CCIO</sub> = 1.8 V ± 5% <sup>(2), (3)</sup>	10	57	108	kΩ
		V <sub>CCIO</sub> = 1.5 V ± 5% <sup>(2), (3)</sup>	13	82	163	kΩ
		V <sub>CCIO</sub> = 1.2 V ± 5% <sup>(2), (3)</sup>	19	143	351	kΩ
R <sub>PD</sub>	Value of the I/O pin pull-down resistor before and during configuration	V <sub>CCIO</sub> = 3.3 V ± 5% <sup>(4)</sup>	6	19	30	kΩ
		V <sub>CCIO</sub> = 3.0 V ± 5% <sup>(4)</sup>	6	22	36	kΩ
		V <sub>CCIO</sub> = 2.5 V ± 5% <sup>(4)</sup>	6	25	43	kΩ
		V <sub>CCIO</sub> = 1.8 V ± 5% <sup>(4)</sup>	7	35	71	kΩ
		V <sub>CCIO</sub> = 1.5 V ± 5% <sup>(4)</sup>	8	50	112	kΩ

### Notes to Table 1-12:

- (1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.
- (2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V<sub>CCIO</sub>.
- (3)  $R_{PU} = (V_{CCIO} - V_I) / I_{R_{PU}}$   
Minimum condition: -40°C; V<sub>CCIO</sub> = V<sub>CC</sub> + 5%, V<sub>I</sub> = V<sub>CC</sub> + 5% - 50 mV;  
Typical condition: 25°C; V<sub>CCIO</sub> = V<sub>CC</sub>, V<sub>I</sub> = 0 V;  
Maximum condition: 100°C; V<sub>CCIO</sub> = V<sub>CC</sub> - 5%, V<sub>I</sub> = 0 V; in which V<sub>I</sub> refers to the input voltage at the I/O pin.
- (4)  $R_{PD} = V_I / I_{R_{PD}}$   
Minimum condition: -40°C; V<sub>CCIO</sub> = V<sub>CC</sub> + 5%, V<sub>I</sub> = 50 mV;  
Typical condition: 25°C; V<sub>CCIO</sub> = V<sub>CC</sub>, V<sub>I</sub> = V<sub>CC</sub> - 5%;  
Maximum condition: 100°C; V<sub>CCIO</sub> = V<sub>CC</sub> - 5%, V<sub>I</sub> = V<sub>CC</sub> - 5%; in which V<sub>I</sub> refers to the input voltage at the I/O pin.

## Hot-Socketing

Table 1-13 lists the hot-socketing specifications for Cyclone IV devices.

**Table 1-13. Hot-Socketing Specifications for Cyclone IV Devices**

Symbol	Parameter	Maximum
I <sub>IOPIN(DC)</sub>	DC current per I/O pin	300 μA
I <sub>IOPIN(AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVRTX(DC)</sub>	DC current per transceiver TX pin	100 mA
I <sub>XCVRRX(DC)</sub>	DC current per transceiver RX pin	50 mA

### Note to Table 1-13:

- (1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |I<sub>IOPIN</sub>| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.



During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.

## Schmitt Trigger Input

Cyclone IV devices support Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF\_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rate. Table 1–14 lists the hysteresis specifications across the supported  $V_{CCIO}$  range for Schmitt trigger inputs in Cyclone IV devices.

**Table 1–14. Hysteresis Specifications for Schmitt Trigger Input in Cyclone IV Devices**

Symbol	Parameter	Conditions (V)	Minimum	Unit
$V_{SCHMITT}$	Hysteresis for Schmitt trigger input	$V_{CCIO} = 3.3$	200	mV
		$V_{CCIO} = 2.5$	200	mV
		$V_{CCIO} = 1.8$	140	mV
		$V_{CCIO} = 1.5$	110	mV

## I/O Standard Specifications

The following tables list input voltage sensitivities ( $V_{IH}$  and  $V_{IL}$ ), output voltage ( $V_{OH}$  and  $V_{OL}$ ), and current drive characteristics ( $I_{OH}$  and  $I_{OL}$ ), for various I/O standards supported by Cyclone IV devices. Table 1–15 through Table 1–20 provide the I/O standard specifications for Cyclone IV devices.

**Table 1–15. Single-Ended I/O Standard Specifications for Cyclone IV Devices <sup>(1), (2)</sup>**

I/O Standard	$V_{CCIO}$ (V)			$V_{IL}$ (V)		$V_{IH}$ (V)		$V_{OL}$ (V)	$V_{OH}$ (V)	$I_{OL}$ (mA) (4)	$I_{OH}$ (mA) (4)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
3.3-V LVTTTL <sup>(3)</sup>	3.135	3.3	3.465	—	0.8	1.7	3.6	0.45	2.4	4	–4
3.3-V LVCMOS <sup>(3)</sup>	3.135	3.3	3.465	—	0.8	1.7	3.6	0.2	$V_{CCIO} - 0.2$	2	–2
3.0-V LVTTTL <sup>(3)</sup>	2.85	3.0	3.15	–0.3	0.8	1.7	$V_{CCIO} + 0.3$	0.45	2.4	4	–4
3.0-V LVCMOS <sup>(3)</sup>	2.85	3.0	3.15	–0.3	0.8	1.7	$V_{CCIO} + 0.3$	0.2	$V_{CCIO} - 0.2$	0.1	–0.1
2.5 V <sup>(3)</sup>	2.375	2.5	2.625	–0.3	0.7	1.7	$V_{CCIO} + 0.3$	0.4	2.0	1	–1
1.8 V	1.71	1.8	1.89	–0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	2.25	0.45	$V_{CCIO} - 0.45$	2	–2
1.5 V	1.425	1.5	1.575	–0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	–2
1.2 V	1.14	1.2	1.26	–0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	–2
3.0-V PCI	2.85	3.0	3.15	—	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	–0.5
3.0-V PCI-X	2.85	3.0	3.15	—	$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	–0.5

**Notes to Table 1–15:**

- (1) For voltage-referenced receiver input waveform and explanation of terms used in Table 1–15, refer to “Glossary” on page 1–37.
- (2) AC load  $CL = 10$  pF
- (3) For more information about interfacing Cyclone IV devices with 3.3/3.0/2.5-V LVTTTL/LVCMOS I/O standards, refer to *AN 447: Interfacing Cyclone III and Cyclone IV Devices with 3.3/3.0/2.5-V LVTTTL/LVCMOS I/O Systems*.
- (4) To meet the  $I_{OL}$  and  $I_{OH}$  specifications, you must set the current strength settings accordingly. For example, to meet the **3.3-V LVTTTL** specification (4 mA), set the current strength settings to 4 mA or higher. Setting at lower current strength may not meet the  $I_{OL}$  and  $I_{OH}$  specifications in the handbook.

**Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices <sup>(1)</sup> (Part 2 of 2)**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>ID</sub> (mV)		V <sub>ICM</sub> (V) <sup>(2)</sup>			V <sub>OD</sub> (mV) <sup>(3)</sup>			V <sub>OS</sub> (V) <sup>(3)</sup>		
	Min	Typ	Max	Min	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVDS (Column I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq 500 \text{ Mbps}$	1.80	247	—	600	1.125	1.25	1.375
						0.55	$500 \text{ Mbps} \leq D_{MAX} \leq 700 \text{ Mbps}$	1.80						
						1.05	$D_{MAX} > 700 \text{ Mbps}$	1.55						
BLVDS (Row I/Os) <sup>(4)</sup>	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
BLVDS (Column I/Os) <sup>(4)</sup>	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
mini-LVDS (Row I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
mini-LVDS (Column I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
RSDS <sup>®</sup> (Row I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
RSDS (Column I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
PPDS (Row I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4
PPDS (Column I/Os) <sup>(5)</sup>	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4

**Notes to Table 1–20:**

- (1) For an explanation of terms used in Table 1–20, refer to “Glossary” on page 1–37.
- (2) V<sub>IN</sub> range:  $0 \text{ V} \leq V_{IN} \leq 1.85 \text{ V}$ .
- (3) R<sub>L</sub> range:  $90 \leq R_L \leq 110 \Omega$ .
- (4) There are no fixed V<sub>IN</sub>, V<sub>OD</sub>, and V<sub>OS</sub> specifications for BLVDS. They depend on the system topology.
- (5) The Mini-LVDS, RSDS, and PPDS standards are only supported at the output pins.
- (6) The LVPECL I/O standard is only supported on dedicated clock input pins. This I/O standard is not supported for output pins.

## Power Consumption

Use the following methods to estimate power for a design:

- the Excel-based EPE
- the Quartus® II PowerPlay power analyzer feature

The interactive Excel-based EPE is used prior to designing the device to get a magnitude estimate of the device power. The Quartus II PowerPlay power analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay power analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, combined with detailed circuit models, can yield very accurate power estimates.



For more information about power estimation tools, refer to the *Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

## Switching Characteristics

This section provides performance characteristics of Cyclone IV core and periphery blocks for commercial grade devices.

These characteristics can be designated as Preliminary or Final.


- Preliminary characteristics are created using simulation results, process data, and other known parameters. The upper-right hand corner of these tables show the designation as “Preliminary”.
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.



**Table 1-21. Transceiver Specification for Cyclone IV GX Devices (Part 3 of 4)**

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Signal detect/loss threshold	PIPE mode	65	—	175	65	—	175	65	—	175	mV
$t_{LTR}$ <sup>(10)</sup>	—	—	—	75	—	—	75	—	—	75	μs
$t_{LTR-LTD\_Manual}$ <sup>(11)</sup>	—	15	—	—	15	—	—	15	—	—	μs
$t_{LTD}$ <sup>(12)</sup>	—	0	100	4000	0	100	4000	0	100	4000	ns
$t_{LTD\_Manual}$ <sup>(13)</sup>	—	—	—	4000	—	—	4000	—	—	4000	ns
$t_{LTD\_Auto}$ <sup>(14)</sup>	—	—	—	4000	—	—	4000	—	—	4000	ns
Receiver buffer and CDR offset cancellation time (per channel)	—	—	—	17000	—	—	17000	—	—	17000	recon fig_c lk cycles
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	—	6	—	dB
<b>Transmitter</b>											
Supported I/O Standards	1.5 V PCML										
Data rate (F324 and smaller package)	—	600	—	2500	600	—	2500	600	—	2500	Mbps
Data rate (F484 and larger package)	—	600	—	3125	600	—	3125	600	—	2500	Mbps
$V_{OCM}$	0.65 V setting	—	650	—	—	650	—	—	650	—	mV
Differential on-chip termination resistors	100-Ω setting	—	100	—	—	100	—	—	100	—	Ω
	150-Ω setting	—	150	—	—	150	—	—	150	—	Ω
Differential and common mode return loss	PIPE, CPRI LV, Serial Rapid I/O SR, SDI, XAUI, SATA	Compliant									—
Rise time	—	50	—	200	50	—	200	50	—	200	ps
Fall time	—	50	—	200	50	—	200	50	—	200	ps
Intra-differential pair skew	—	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block skew	—	—	—	120	—	—	120	—	—	120	ps

Figure 1-2 shows the lock time parameters in manual mode.

 LTD = lock-to-data. LTR = lock-to-reference.

**Figure 1-2. Lock Time Parameters for Manual Mode**

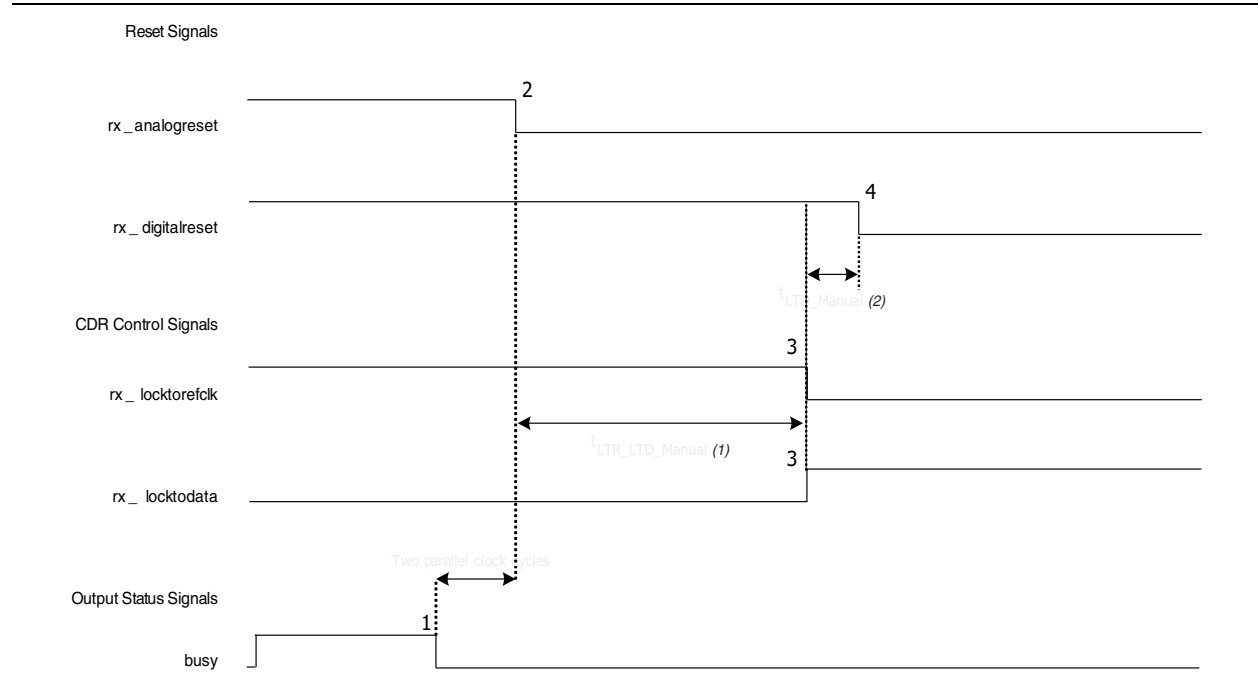
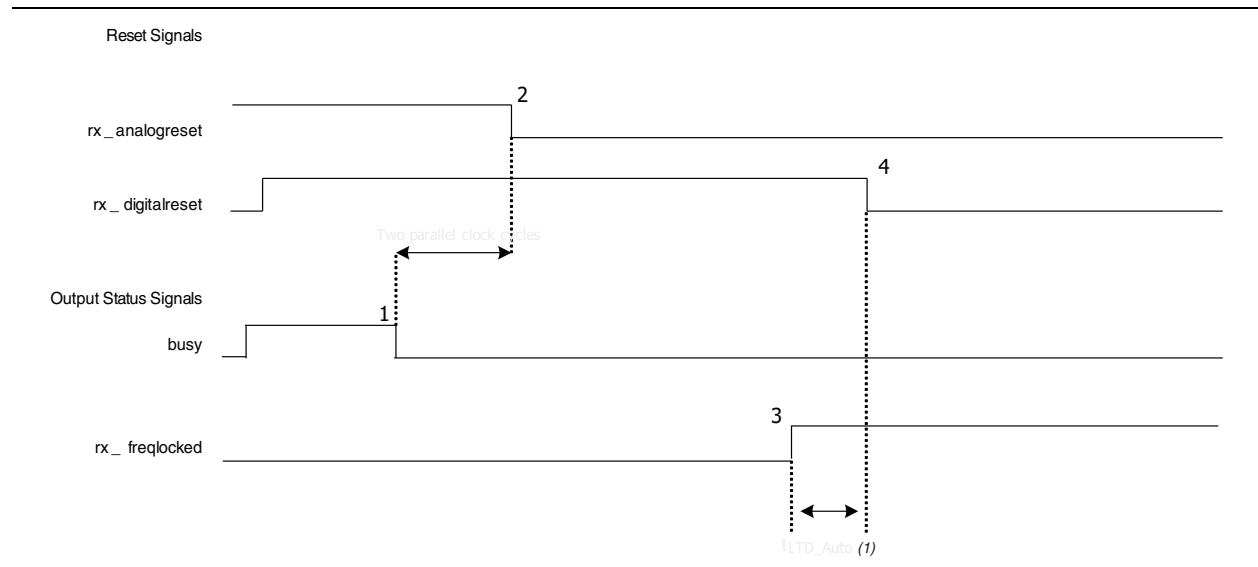


Figure 1-3 shows the lock time parameters in automatic mode.

**Figure 1-3. Lock Time Parameters for Automatic Mode**



## Embedded Multiplier Specifications

Table 1–26 lists the embedded multiplier specifications for Cyclone IV devices.

**Table 1–26. Embedded Multiplier Specifications for Cyclone IV Devices**

Mode	Resources Used	Performance					Unit
	Number of Multipliers	C6	C7, I7, A7	C8	C8L, I8L	C9L	
9 × 9-bit multiplier	1	340	300	260	240	175	MHz
18 × 18-bit multiplier	1	287	250	200	185	135	MHz

## Memory Block Specifications

Table 1–27 lists the M9K memory block specifications for Cyclone IV devices.

**Table 1–27. Memory Block Performance Specifications for Cyclone IV Devices**

Memory	Mode	Resources Used		Performance					Unit
		LEs	M9K Memory	C6	C7, I7, A7	C8	C8L, I8L	C9L	
M9K Block	FIFO 256 × 36	47	1	315	274	238	200	157	MHz
	Single-port 256 × 36	0	1	315	274	238	200	157	MHz
	Simple dual-port 256 × 36 CLK	0	1	315	274	238	200	157	MHz
	True dual port 512 × 18 single CLK	0	1	315	274	238	200	157	MHz

## Configuration and JTAG Specifications

Table 1–28 lists the configuration mode specifications for Cyclone IV devices.

**Table 1–28. Passive Configuration Mode Specifications for Cyclone IV Devices <sup>(1)</sup>**

Programming Mode	V <sub>CCINT</sub> Voltage Level (V)	DCLK f <sub>MAX</sub>	Unit
Passive Serial (PS)	1.0 <sup>(3)</sup>	66	MHz
	1.2	133	MHz
Fast Passive Parallel (FPP) <sup>(2)</sup>	1.0 <sup>(3)</sup>	66	MHz
	1.2 <sup>(4)</sup>	100	MHz

**Notes to Table 1–28:**

- (1) For more information about PS and FPP configuration timing parameters, refer to the *Configuration and Remote System Upgrades in Cyclone IV Devices* chapter.
- (2) FPP configuration mode supports all Cyclone IV E devices (except for E144 package devices) and EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 only.
- (3) V<sub>CCINT</sub> = 1.0 V is only supported for Cyclone IV E 1.0 V core voltage devices.
- (4) Cyclone IV E devices support 1.2 V V<sub>CCINT</sub>. Cyclone IV E 1.2 V core voltage devices support 133 MHz DCLK f<sub>MAX</sub> for EP4CE6, EP4CE10, EP4CE15, EP4CE22, EP4CE30, and EP4CE40 only.

**Table 1-31. RSDS Transmitter Timing Specifications for Cyclone IV Devices <sup>(1), (2), (4)</sup> (Part 2 of 2)**

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t <sub>LOCK</sub> <sup>(3)</sup>	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

**Notes to Table 1-31:**

- (1) Applicable for true RSDS and emulated RSDS\_E\_3R transmitter.
- (2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks.  
Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (3) t<sub>LOCK</sub> is the time required for the PLL to lock from the end-of-device configuration.
- (4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

**Table 1-32. Emulated RSDS\_E\_1R Transmitter Timing Specifications for Cyclone IV Devices <sup>(1), (3)</sup> (Part 1 of 2)**

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f <sub>HCLK</sub> (input clock frequency)	×10	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×8	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×7	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×4	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×2	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×1	5	—	170	5	—	170	5	—	170	5	—	170	5	—	145	MHz
Device operation in Mbps	×10	100	—	170	100	—	170	100	—	170	100	—	170	100	—	145	Mbps
	×8	80	—	170	80	—	170	80	—	170	80	—	170	80	—	145	Mbps
	×7	70	—	170	70	—	170	70	—	170	70	—	170	70	—	145	Mbps
	×4	40	—	170	40	—	170	40	—	170	40	—	170	40	—	145	Mbps
	×2	20	—	170	20	—	170	20	—	170	20	—	170	20	—	145	Mbps
	×1	10	—	170	10	—	170	10	—	170	10	—	170	10	—	145	Mbps
t <sub>DUTY</sub>	—	45	—	55	45	—	55	45	—	55	45	—	55	45	—	55	%
TCCS	—	—	—	200	—	—	200	—	—	200	—	—	200	—	—	200	ps
Output jitter (peak to peak)	—	—	—	500	—	—	500	—	—	550	—	—	600	—	—	700	ps
t <sub>RISE</sub>	20 – 80%, C <sub>LOAD</sub> = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
t <sub>FALL</sub>	20 – 80%, C <sub>LOAD</sub> = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps

**Table 1–32. Emulated RSDS\_E\_1R Transmitter Timing Specifications for Cyclone IV Devices <sup>(1), (3)</sup> (Part 2 of 2)**

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{\text{LOCK}}$ <sup>(2)</sup>	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

**Notes to Table 1–32:**

- (1) Emulated RSDS\_E\_1R transmitter is supported at the output pin of all I/O Banks of Cyclone IV E devices and I/O Banks 3, 4, 5, 6, 7, 8, and 9 of Cyclone IV GX devices.
- (2)  $t_{\text{LOCK}}$  is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

**Table 1–33. Mini-LVDS Transmitter Timing Specifications for Cyclone IV Devices <sup>(1), (2), (4)</sup>**

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{HSCLK}}$ (input clock frequency)	×10	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×8	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×7	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×4	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×2	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×1	5	—	400	5	—	311	5	—	311	5	—	311	5	—	265	MHz
Device operation in Mbps	×10	100	—	400	100	—	311	100	—	311	100	—	311	100	—	265	Mbps
	×8	80	—	400	80	—	311	80	—	311	80	—	311	80	—	265	Mbps
	×7	70	—	400	70	—	311	70	—	311	70	—	311	70	—	265	Mbps
	×4	40	—	400	40	—	311	40	—	311	40	—	311	40	—	265	Mbps
	×2	20	—	400	20	—	311	20	—	311	20	—	311	20	—	265	Mbps
	×1	10	—	400	10	—	311	10	—	311	10	—	311	10	—	265	Mbps
$t_{\text{DUTY}}$	—	45	—	55	45	—	55	45	—	55	45	—	55	45	—	55	%
TCCS	—	—	—	200	—	—	200	—	—	200	—	—	200	—	—	200	ps
Output jitter (peak to peak)	—	—	—	500	—	—	500	—	—	550	—	—	600	—	—	700	ps
$t_{\text{RISE}}$	20 – 80%, $C_{\text{LOAD}} = 5 \text{ pF}$	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
$t_{\text{FALL}}$	20 – 80%, $C_{\text{LOAD}} = 5 \text{ pF}$	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
$t_{\text{LOCK}}$ <sup>(3)</sup>	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

**Notes to Table 1–33:**

- (1) Applicable for true and emulated mini-LVDS transmitter.
- (2) Cyclone IV E—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated mini-LVDS transmitter is supported at the output pin of all I/O banks.  
Cyclone IV GX—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (3)  $t_{\text{LOCK}}$  is the time required for the PLL to lock from the end-of-device configuration.
- (4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

**Table 1–34. True LVDS Transmitter Timing Specifications for Cyclone IV Devices <sup>(1)</sup>, <sup>(3)</sup>**

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>HCLK</sub> (input clock frequency)	×10	5	420	5	370	5	320	5	320	5	250	MHz
	×8	5	420	5	370	5	320	5	320	5	250	MHz
	×7	5	420	5	370	5	320	5	320	5	250	MHz
	×4	5	420	5	370	5	320	5	320	5	250	MHz
	×2	5	420	5	370	5	320	5	320	5	250	MHz
	×1	5	420	5	402.5	5	402.5	5	362	5	265	MHz
HSIODR	×10	100	840	100	740	100	640	100	640	100	500	Mbps
	×8	80	840	80	740	80	640	80	640	80	500	Mbps
	×7	70	840	70	740	70	640	70	640	70	500	Mbps
	×4	40	840	40	740	40	640	40	640	40	500	Mbps
	×2	20	840	20	740	20	640	20	640	20	500	Mbps
	×1	10	420	10	402.5	10	402.5	10	362	10	265	Mbps
t <sub>DUTY</sub>	—	45	55	45	55	45	55	45	55	45	55	%
TCCS	—	—	200	—	200	—	200	—	200	—	200	ps
Output jitter (peak to peak)	—	—	500	—	500	—	550	—	600	—	700	ps
t <sub>LOCK</sub> <sup>(2)</sup>	—	—	1	—	1	—	1	—	1	—	1	ms

**Notes to Table 1–34:**

- (1) Cyclone IV E—true LVDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Cyclone IV GX—true LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6.
- (2) t<sub>LOCK</sub> is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

**Table 1–35. Emulated LVDS Transmitter Timing Specifications for Cyclone IV Devices <sup>(1)</sup>, <sup>(3)</sup> (Part 1 of 2)**

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>HCLK</sub> (input clock frequency)	×10	5	320	5	320	5	275	5	275	5	250	MHz
	×8	5	320	5	320	5	275	5	275	5	250	MHz
	×7	5	320	5	320	5	275	5	275	5	250	MHz
	×4	5	320	5	320	5	275	5	275	5	250	MHz
	×2	5	320	5	320	5	275	5	275	5	250	MHz
	×1	5	402.5	5	402.5	5	402.5	5	362	5	265	MHz
HSIODR	×10	100	640	100	640	100	550	100	550	100	500	Mbps
	×8	80	640	80	640	80	550	80	550	80	500	Mbps
	×7	70	640	70	640	70	550	70	550	70	500	Mbps
	×4	40	640	40	640	40	550	40	550	40	500	Mbps
	×2	20	640	20	640	20	550	20	550	20	500	Mbps
	×1	10	402.5	10	402.5	10	402.5	10	362	10	265	Mbps

**Table 1–35. Emulated LVDS Transmitter Timing Specifications for Cyclone IV Devices <sup>(1), (3)</sup> (Part 2 of 2)**

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>DUTY</sub>	—	45	55	45	55	45	55	45	55	45	55	%
TCCS	—	—	200	—	200	—	200	—	200	—	200	ps
Output jitter (peak to peak)	—	—	500	—	500	—	550	—	600	—	700	ps
t <sub>LOCK</sub> <sup>(2)</sup>	—	—	1	—	1	—	1	—	1	—	1	ms

**Notes to Table 1–35:**

- (1) Cyclone IV E—emulated LVDS transmitter is supported at the output pin of all I/O Banks.  
Cyclone IV GX—emulated LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (2) t<sub>LOCK</sub> is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

**Table 1–36. LVDS Receiver Timing Specifications for Cyclone IV Devices <sup>(1), (3)</sup>**

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>HCLK</sub> (input clock frequency)	×10	10	437.5	10	370	10	320	10	320	10	250	MHz
	×8	10	437.5	10	370	10	320	10	320	10	250	MHz
	×7	10	437.5	10	370	10	320	10	320	10	250	MHz
	×4	10	437.5	10	370	10	320	10	320	10	250	MHz
	×2	10	437.5	10	370	10	320	10	320	10	250	MHz
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	MHz
HSIODR	×10	100	875	100	740	100	640	100	640	100	500	Mbps
	×8	80	875	80	740	80	640	80	640	80	500	Mbps
	×7	70	875	70	740	70	640	70	640	70	500	Mbps
	×4	40	875	40	740	40	640	40	640	40	500	Mbps
	×2	20	875	20	740	20	640	20	640	20	500	Mbps
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	Mbps
SW	—	—	400	—	400	—	400	—	550	—	640	ps
Input jitter tolerance	—	—	500	—	500	—	550	—	600	—	700	ps
t <sub>LOCK</sub> <sup>(2)</sup>	—	—	1	—	1	—	1	—	1	—	1	ms

**Notes to Table 1–36:**

- (1) Cyclone IV E—LVDS receiver is supported at all I/O Banks.  
Cyclone IV GX—LVDS receiver is supported at I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (2) t<sub>LOCK</sub> is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

## External Memory Interface Specifications

The external memory interfaces for Cyclone IV devices are auto-calibrating and easy to implement.

For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1–37 lists the memory output clock jitter specifications for Cyclone IV devices.

**Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices <sup>(1), (2)</sup>**

Parameter	Symbol	Min	Max	Unit
Clock period jitter	$t_{JIT(per)}$	–125	125	ps
Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–200	200	ps
Duty cycle jitter	$t_{JIT(duty)}$	–150	150	ps

**Notes to Table 1–37:**

- (1) Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.
- (2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

## Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

**Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins <sup>(1), (2), (3)</sup>**

Symbol	C6		C7, I7		C8, I8L, A7		C9L		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

**Notes to Table 1–38:**

- (1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.
- (2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

## OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

**Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices <sup>(1)</sup>**

Symbol	Description	Maximum	Units
$t_{OCTCAL}$	Duration of series OCT with calibration at device power-up	20	μs

**Note to Table 1–39:**

- (1) OCT calibration takes place after device configuration and before entering user mode.



Table 1–42 and Table 1–43 list the IOE programmable delay for Cyclone IV E 1.2 V core voltage devices.

**Table 1–42. IOE Programmable Delay on Column Pins for Cyclone IV E 1.2 V Core Voltage Devices <sup>(1), (2)</sup>**

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset								Unit
				Fast Corner			Slow Corner					
				C6	I7	A7	C6	C7	C8	I7	A7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.314	1.211	1.211	2.177	2.340	2.433	2.388	2.508	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.307	1.203	1.203	2.19	2.387	2.540	2.430	2.545	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.437	0.402	0.402	0.747	0.820	0.880	0.834	0.873	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.693	0.665	0.665	1.200	1.379	1.532	1.393	1.441	ns

**Notes to Table 1–42:**

- (1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

**Table 1–43. IOE Programmable Delay on Row Pins for Cyclone IV E 1.2 V Core Voltage Devices <sup>(1), (2)</sup>**

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset								Unit
				Fast Corner			Slow Corner					
				C6	I7	A7	C6	C7	C8	I7	A7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.314	1.209	1.209	2.201	2.386	2.510	2.429	2.548	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.312	1.207	1.207	2.202	2.402	2.558	2.447	2.557	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.458	0.419	0.419	0.783	0.861	0.924	0.875	0.915	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.686	0.657	0.657	1.185	1.360	1.506	1.376	1.422	ns

**Notes to Table 1–43:**

- (1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

Table 1–44 and Table 1–45 list the IOE programmable delay for Cyclone IV GX devices.

**Table 1–44. IOE Programmable Delay on Column Pins for Cyclone IV GX Devices <sup>(1), (2)</sup>**

Parameter	Paths Affected	Number of Settings	Min Offset	Max Offset						Unit
				Fast Corner		Slow Corner				
				C6	I7	C6	C7	C8	I7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.313	1.209	2.184	2.336	2.451	2.387	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.312	1.208	2.200	2.399	2.554	2.446	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.438	0.404	0.751	0.825	0.886	0.839	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.713	0.682	1.228	1.41	1.566	1.424	ns

**Notes to Table 1–44:**

- (1) The incremental values for the settings are generally linear. For exact values of each setting, use the latest version of the Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

**Table 1–45. IOE Programmable Delay on Row Pins for Cyclone IV GX Devices <sup>(1), (2)</sup>**

Parameter	Paths Affected	Number of Settings	Min Offset	Max Offset						Unit
				Fast Corner		Slow Corner				
				C6	I7	C6	C7	C8	I7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.314	1.210	2.209	2.398	2.526	2.443	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.313	1.208	2.205	2.406	2.563	2.450	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.461	0.421	0.789	0.869	0.933	0.884	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.712	0.682	1.225	1.407	1.562	1.421	ns

**Notes to Table 1–45:**

- (1) The incremental values for the settings are generally linear. For exact values of each setting, use the latest version of Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software

Table 1-46. Glossary (Part 2 of 5)

Letter	Term	Definitions
<b>J</b>	JTAG Waveform	<p>The diagram illustrates the JTAG waveform with the following timing parameters:</p> <ul style="list-style-type: none"> <li><math>t_{JCP}</math>: Time from TCK rising edge to TMS falling edge.</li> <li><math>t_{JCH}</math>: Time from TCK rising edge to TDI falling edge.</li> <li><math>t_{JCL}</math>: Time from TCK rising edge to TDI rising edge.</li> <li><math>t_{JPSU\_TDI}</math>: Time from TCK rising edge to TDI setup time.</li> <li><math>t_{JPSU\_TMS}</math>: Time from TCK rising edge to TMS setup time.</li> <li><math>t_{JPH}</math>: Time from TCK rising edge to TMS hold time.</li> <li><math>t_{JPZX}</math>: Time from TCK rising edge to TDO setup time.</li> <li><math>t_{JPCO}</math>: Time from TCK rising edge to TDO output delay.</li> <li><math>t_{JPXZ}</math>: Time from TCK rising edge to TDO hold time.</li> <li><math>t_{JSSU}</math>: Time from TCK rising edge to Signal to be Captured setup time.</li> <li><math>t_{JSH}</math>: Time from TCK rising edge to Signal to be Captured hold time.</li> <li><math>t_{JSZX}</math>: Time from TCK rising edge to Signal to be Driven setup time.</li> <li><math>t_{JSCO}</math>: Time from TCK rising edge to Signal to be Driven output delay.</li> <li><math>t_{JSXZ}</math>: Time from TCK rising edge to Signal to be Driven hold time.</li> </ul>
<b>K</b>	—	—
<b>L</b>	—	—
<b>M</b>	—	—
<b>N</b>	—	—
<b>O</b>	—	—
<b>P</b>	PLL Block	<p>The following highlights the PLL specification parameters:</p> <p>The diagram shows the PLL block architecture with the following components and signals:</p> <ul style="list-style-type: none"> <li><b>Inputs:</b> CLK, Core Clock.</li> <li><b>Internal Blocks:</b> Switchover, PFD (Phase-Frequency Divider), CP (Charge Pump), LF (Loop Filter), VCO (Voltage-Controlled Oscillator), Counters C0..C4, Phase tap, M (Modulator).</li> <li><b>Signals:</b> <math>f_{IN}</math>, <math>f_{INPFD}</math>, <math>f_{VCO}</math>, <math>f_{OUT\_EXT}</math>, <math>f_{OUT}</math>, GCLK.</li> </ul> <p><b>Key:</b></p> <ul style="list-style-type: none"> <li>Reconfigurable in User Mode</li> </ul>
<b>Q</b>	—	—

## Document Revision History

Table 1-47 lists the revision history for this chapter.

**Table 1-47. Document Revision History**

Date	Version	Changes
March 2016	2.0	Updated note (5) in Table 1-21 to remove support for the N148 package.
October 2014	1.9	Updated maximum value for $V_{CCD\_PLL}$ in Table 1-1. Removed extended temperature note in Table 1-3.
December 2013	1.8	Updated Table 1-21 by adding Note (15).
May 2013	1.7	Updated Table 1-15 by adding Note (4).
October 2012	1.6	<ul style="list-style-type: none"> <li>■ Updated the maximum value for <math>V_I</math>, <math>V_{CCD\_PLL}</math>, <math>V_{CCIO}</math>, <math>V_{CC\_CLKIN}</math>, <math>V_{CCH\_GXB}</math>, and <math>V_{CCA\_GXB}</math> in Table 1-1.</li> <li>■ Updated Table 1-11 and Table 1-22.</li> <li>■ Updated Table 1-21 to include peak-to-peak differential input voltage for the Cyclone IV GX transceiver input reference clock.</li> <li>■ Updated Table 1-29 to include the typical <math>DCLK</math> value.</li> <li>■ Updated the minimum <math>f_{HCLK}</math> value in Table 1-31, Table 1-32, Table 1-33, Table 1-34, and Table 1-35.</li> </ul>
November 2011	1.5	<ul style="list-style-type: none"> <li>■ Updated “Maximum Allowed Overshoot or Undershoot Voltage”, “Operating Conditions”, and “PLL Specifications” sections.</li> <li>■ Updated Table 1-2, Table 1-3, Table 1-4, Table 1-5, Table 1-8, Table 1-9, Table 1-15, Table 1-18, Table 1-19, and Table 1-21.</li> <li>■ Updated Figure 1-1.</li> </ul>
December 2010	1.4	<ul style="list-style-type: none"> <li>■ Updated for the Quartus II software version 10.1 release.</li> <li>■ Updated Table 1-21 and Table 1-25.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.3	<p>Updated for the Quartus II software version 10.0 release:</p> <ul style="list-style-type: none"> <li>■ Updated Table 1-3, Table 1-4, Table 1-21, Table 1-25, Table 1-28, Table 1-30, Table 1-40, Table 1-41, Table 1-42, Table 1-43, Table 1-44, and Table 1-45.</li> <li>■ Updated Figure 1-2 and Figure 1-3.</li> <li>■ Removed SW Requirement and TCCS for Cyclone IV Devices tables.</li> <li>■ Minor text edits.</li> </ul>
March 2010	1.2	<p>Updated to include automotive devices:</p> <ul style="list-style-type: none"> <li>■ Updated the “Operating Conditions” and “PLL Specifications” sections.</li> <li>■ Updated Table 1-1, Table 1-8, Table 1-9, Table 1-21, Table 1-26, Table 1-27, Table 1-31, Table 1-32, Table 1-33, Table 1-34, Table 1-35, Table 1-36, Table 1-37, Table 1-38, Table 1-40, Table 1-42, and Table 1-43.</li> <li>■ Added Table 1-5 to include ESD for Cyclone IV devices GPIOs and HSSI I/Os.</li> <li>■ Added Table 1-44 and Table 1-45 to include IOE programmable delay for Cyclone IV E 1.2 V core voltage devices.</li> <li>■ Minor text edits.</li> </ul>

